

Features

- ♦ Compact design, 0603 size, surface mount type
- ♦ Low-profile
- ♦ Fast response for fault protection
- ♦ Low thermal derating factor
- ♦ RoHS compliant ^[1]
- ♦ Halogen free ^[2]

Applications

- ♦ Resettable fault protection of general electronics equipment

Electrical Performance

Vmax (Vdc)	Imax (Amperes)	Current Rating**		Time to Trip**	Resistance		Tripped State Power Dissipation**
		Amperes @25°C		Seconds @25°C 8.00A	Ohms @25°C		Watts @25°C 6.0Vdc
		Ihold	Itrip	Max	Rmin	R1max*	Max
6.0	40.0	0.75	1.50	0.10	0.060	0.450	0.5

*Maximum Resistance is measured 1 hour after reflow

**Values specified were determined using PCB's with 0.020"x1.5oz copper traces.

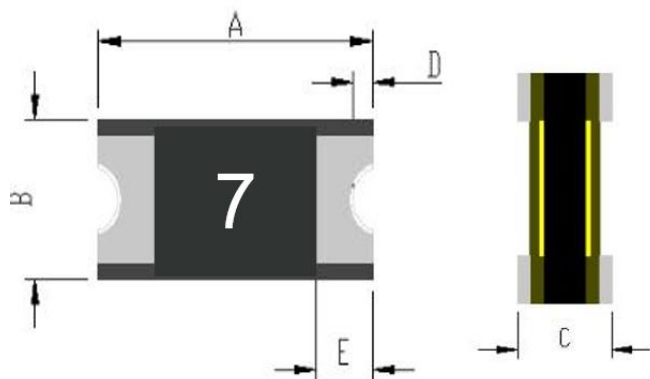
Thermal Derating--Hold current (A) at Ambient Temperature (°C) (for reference only)

Ambient Operation Temperature(°C)	-40°C	-20°C	0°C	+25°C	+40°C	+50°C	+60°C	+70°C	+85°C
Hold Current (A)	0.980	0.850	0.810	0.750	0.600	0.540	0.440	0.400	0.310

Environmental Characteristics

Test	Test Conditions	Accept/Reject Criteria
Operating Temperature	-40°C to +85°C	
Recommended Storage	+40°C max/70% R.H. max	
Maximum Device Surface Temperature in Tripped State	125°C	
Passive Aging	+85°C, 1000 hours	+/-5% typical resistance change
Humidity Aging	+85°C, 85% R.H., 100 hours	+/-5% typical resistance change
Thermal Shock	+85°C/-40°C 20 times	-30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-883, Method 2007, Condition A	No change
Moisture Sensitivity Level	J-STD-020	Level 1

Dimensions



Dimensions MM (INCH)		
Dimension	Min	Max
A	1.45 (0.057)	1.85 (0.073)
B	0.65 (0.026)	1.05 (0.041)
C	0.50 (0.020)	1.00 (0.039)
D	0.05 (0.002)	-- (--)
E	0.15 (0.006)	0.50 (0.020)

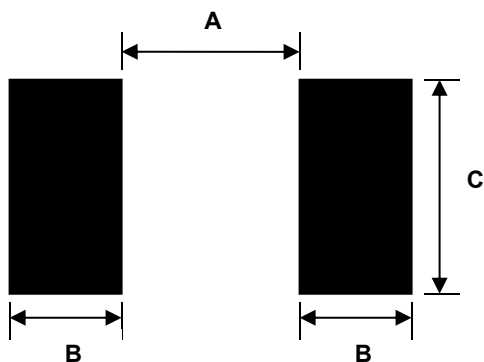
Terminal Material:

100% Matte Tin with Nickel Underplate

Lead Solderability:

Meets ANSI/J-STD-002, Category 3.

Pads Layout (Recommended)



Recommended Pad Layout Figures		
A	B	C
NOM	NOM	NOM
mm: 1.00	#48	#50
inch (0.039)	(0.039)	(0.031)

Can be soldered using standard Pb-free reflow profile.



Warnings:

- ♦ Electrical performance can differ according to installation condition of the device. Users shall independently assess the suitability of the device under actual using condition.
- ♦ Operation beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or flame.
- ♦ These devices are intended to protect against the effects of temporary overcurrent or over-temperature fault conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration.
- ♦ Avoid the exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials.
- ♦ These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses.
- ♦ Circuits with inductance may generate a voltage ($L di/dt$) above the rated voltage of the PTCs device.